

RENESAS TECHNICAL UPDATE

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Product Category	User Development Environment		Document No.	TN-CSX-079A/EA	Rev.	1.0
Title	Update of the Integrated Development Environment (HEW3) V.3.01.04		Information Category	Specification Change		
Applicable Product	All products that include HEW3	Lot No.	Reference Document	High-performance Embedded Workshop 3 User's Manual Rev.2.00 REJ10B0025-0200H (For SH) REJ10B0026-0200H (For H8)		
		HEW V2.2 HEW V3.x				

HEW3 (High-performance Embedded Workshop 3) is updated to V.3.01.04.

Download the update tool from the following URL:

<http://www.renesas.com/eng/products/mpumcu/tool/index.html>

The products including HEW V2.2 and V3.x can be updated.

Details on this update are listed below.

1. Release of the restriction of HEW V.3.01.02

We have corrected the following problems:

(1) Restriction of MAP Display

The "Linker section setting information" on a MAP window isn't displayed.

(2) Restrictions of Virtual Desktop function

Don't open memory window on more than two window configurations of virtual desktop function.

(3) Restriction of the "Include map file:" option (SH only)

A link error might occur when "Include map file:" was specified on the C/C++ tab of the Tools Options Dialog Box.